


## Standardized Information for Process/Product Change Notification (PCN)

1. PCN basic data			
1.1 Company	 TAIWAN SEMICONDUCTOR		
1.2 PCN No.	PCN17019		
1.3 Title of PCN	Change of die size and change HF molding compound source		
1.4 Product Category	Active Components - Discrete Components ▼		
1.5 Issue date	2017/07/17		
1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)	

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	Sunnies Pan	
2.1.2 Phone	+886-2-8913-1588 Ext:2205	
2.1.3 Email	sunnies@mail.ts.com.tw	
2.2 Team supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)
Stanley Lin	886-2-8913-1588 Ext.2104	stanleylin@mail.ts.com.tw
Celia Huang	886-2-8913-1588 Ext.2125	celia@mail.ts.com.tw

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PW-02	PROCESS - WAFER PRODUCTION	New wafer diameter
#2	SEM-PW-03	PROCESS - WAFER PRODUCTION	New final wafer thickness
#3	SEM-PA-11	PROCESS - ASSEMBLY	Change of mold compound / encapsulation material
#4			
#5			

4. Description of change		
	Old	New
Change #1	SOD-723F Dice size and thickness: 0.37*0.37*0.18mm*1pcs	SOD-723F Dice size and thickness: 0.23*0.23*0.16mm*2pcs
Change #2	SOD-523F&SOD-723F HF molding compound Supplier : A Type : A	SOD-523F&SOD-723F HF molding compound Supplier : B Type : B
Change #3	SOT-23 & SOT-323 & SOD-123F HF molding compound Supplier : A Type : A	SOT-23 & SOT-323 & SOD-123F HF molding compound Supplier : C Type : C
Change #4	SOD-323F HF molding compound Supplier : A Type : A	SOD-323F HF molding compound Supplier : D Type : D
Change #5		
4.6 Anticipated impact on form, fit, function, reliability or processability?	Not impact the form, fit, function, reliability or processability	
4.7 Reference parts with customer number (optional)		

5. Reason / motivation for change	
5.1 Motivation	Molding compound & Dice size & Thickness change
5.2 Additional explanation (optional)	

6. Marking of parts / traceability of change	
6.1 Description	Use date code to control

Form provided by ZVEI - Revision 3.0.0

[illegible]

**Customer Feedback/Approval Form**

Form provided by ZVEI - Revision 3.0.0

<b>Title of PCN:</b>			
Change of die size and change HF molding compound source			
<b>Customer PCN No.</b>		<b>Supplier PCN No.</b>	<b>PCN17019</b>
<b>Please check the appropriate box below:</b>			

<input type="checkbox"/>	<b>1. Feedback</b>	<b>date:</b>	
<input type="checkbox"/>	We agree with this proposed change for the parts as listed in chapter '11. Affected parts'. Approval letter will be sent in written form.		
<input type="checkbox"/>	We agree with this proposed change schedule and will start with the PCN process. Approval letter will be sent in written form after evaluation.		
<input type="checkbox"/>	<b>We disapprove because:</b>		
<input type="checkbox"/>	<b>Remark:</b>		

<input type="checkbox"/>	<b>2. Feedback</b>	<b>date:</b>	
<input type="checkbox"/>	We acknowledge qualification / validation as assigned in chapter 8 of the PCN.		
<input type="checkbox"/>	<b>We need more information:</b>		
<input type="checkbox"/>	<b>We need the following samples:</b>		
<input type="checkbox"/>	<b>Estimated closing date for PCN:</b>		

<input type="checkbox"/>	<b>Final Feedback/Approval</b>	<b>date:</b>	

<b>Sender:</b>	
<b>Company:</b>	

<b>Name:</b>	
<b>Address/Location:</b>	
<b>Signature:</b>	
<b>Date:</b>	

<b>Please return to: [your Sales partner]</b>	
<b>Name:</b>	
<b>Address/Location:</b>	
<b>Phone:</b>	
<b>Fax:</b>	
<b>Email:</b>	



